

Metal-clad base materials for printed wiring boards —

**Part 103: Special materials used in
connection with printed circuits —**

**Section 103.3 Specification for
permanent polymer coating materials
(solder resist) for use in the fabrication
of printed boards**

Committees responsible for this British Standard

The preparation of this British Standard was entrusted by the Electronic Components Standards Policy Committee (ECL/-) to Technical Committee ECL/19, upon which the following bodies were represented:

- British Telecommunications plc
- ERA Technology Ltd.
- Electrical and Electronic Insulation Association (BEAMA Ltd.)
- Electronic Components Industry Federation
- Electronic Engineering Association
- GAMBICA (BEAMA Ltd.)
- Institute of Circuit Technology
- Institute of Metal Finishing
- Institution of Production Engineers
- Ministry of Defence
- National Supervising Inspectorate
- Printed Circuit Association
- Telecommunication Engineering and Manufacturing Association (TEMA)

This British Standard, having been prepared under the direction of the Electronic Components Standards Policy Committee, was published under the authority of the Standards Board and comes into effect on 31 March 1992

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The following BSI references relate to the work on this standard:
Committee reference ECL/19
Special announcement in *BSI News* December 1991

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Amendments issued since publication

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National foreword

This Section of BS 4584 has been prepared under the direction of the Electronic Components Standards Policy Committee. It is identical with IEC 249-3-3:1991 “Base materials for printed circuits” Part 3: “Special materials used in connection with printed circuits”, Specification No. 3: “Permanent polymer materials (solder resist) for use in the fabrication of printed boards”, published by the International Electrotechnical Commission (IEC).

This Section is one of a series of specifications for base materials for printed circuits. This series of specifications replaces the previously published Parts of BS 4584 which are listed below. The following list provides a guide to the relation between these withdrawn Parts and the new specifications. Note that inclusion in the list does not necessarily indicate an exact correspondence between the Parts but only a technical relationship.

Withdrawn Part	Replacement Section
2(1972)	102.4(1990)
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Apart from implementing IEC 249-3-3:1991 as a dual-numbered specification, this new Section of BS 4584 also supersedes BS 6096-3:1981 and BS 6096-4:1981, which are withdrawn.

Cross-references

International standard	Corresponding British Standard
IEC 68-2-2:1974	BS 2011 Environmental testing Part 2.1B: 1977 Tests B. Dry heat (Identical)
IEC 68-2-3:1969	Part 2.1Ca: 1977 Test Ca. Damp heat, steady state (Identical)
IEC 68-2-14:1984	Part 2.1N: 1985 Test N. Change of temperature (Identical)
IEC 68-2-20:1979	Part 2.1T: 1981 Test T. Soldering (Identical)
IEC 68-2-38:1974	Part 2.1Z/AD: 1977 Test Z/AD. Composite temperature/humidity cyclic test (Identical)
IEC 112:1979	BS 5901:1980 Method of test for determining the comparative and the proof tracking indices of solid insulating materials under moist conditions (Identical)
IEC 249-1:1982	BS 4584 Metal-clad materials for printed wiring boards Part 1:1983 Methods of test (Identical)
IEC 249-2-5:1987	Section 102.5:1990 Specification for epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test) (Identical)
IEC 249-2-7:1987	Section 102.7:1990 Specification for phenolic cellulose copper-clad laminated sheet of defined flammability (vertical burning test) (Identical)
IEC 326-2:1990	BS 6221 Printed wiring boards Part 2:1991 Methods of test (Identical)
IEC 326-6:1980	Part 6:1982 Method for specifying multilayer printed wiring boards (Identical)
IEC 426:1973	BS 5735:1979 Test methods for determining electrolytic corrosion with electrical insulating materials (Identical)

The Technical Committee has reviewed the provisions of IEC 194, IEC 250, IEC 326-2 and ISO 2409, to which reference is made in the text, and has decided that they are acceptable for use in conjunction with this standard.

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

Compliance with a British Standard does not of itself confer immunity from legal obligations.

Summary of pages

This document comprises a front cover, an inside front cover, pages i to iv, pages 1 to 12, an inside back cover and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

